ELC 720
LASER PLATFORMS FOR ELECTRONICS

ELC 720
Laser Platforms for Electronics
### TECHNICAL SPECIFICATIONS

<table>
<thead>
<tr>
<th>ELC 720</th>
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<tbody>
<tr>
<td>Dimensions (L x W x H)</td>
<td>2,900 mm x 2,800 mm x 2,700 mm</td>
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<tr>
<td>Weight</td>
<td>5,000 - 5,500 kg</td>
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<tr>
<td>Power supply</td>
<td>200 - 480 V</td>
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<tr>
<td>Compressed dry air</td>
<td>6 - 7 bar</td>
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<tr>
<td>Cooling Water</td>
<td>5 - 20 l/min</td>
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</table>
| Working area | 2 x 2 chucks  
Scan field 60 mm x 60 mm |
| Accuracy | < ±20 μm absolute  
< ±10 μm repeatability |
| Available laser sources | Wave length  
10.6 μm (CO₂)  
1,030 nm  
Pulse | μs; ps |
| Laser spot size | 2 - 300 μm |
| Beam delivery | Scanner; Fixed optics |
| Safety | CE |

### PROCESS AND SYSTEM VALUES

- Material: polished plane Sapphire (c-plane)
- Material thicknesses: < 0.4 mm
- Sidewall roughness values: ~ 0.4 μm
- Maximum product size: 2”
- Throughput: up to 40 pcs per minute (depending on layout)
- No HAZ
- Taper: < 2”

### PROCESS AND SYSTEM LIMITATIONS

- Minimum space between neighboring caps is 750 μm

### FEATURES

- Universal cutting system
- Highly modular system design
- Fast manufacturing
- High volumes and quick ramp-up
- Highly accurate system
- Standalone and line integrable system
- Linear / free form
- Up to 2 x scanner heads
- Up to 2 x fixed optics
- Up to three laser sources in one machine

### OPTIONAL

- Fully automatic handling (Production)
- Semi-automatic handling (R&D)
- MES interface
- Integrated process metrology
- Import of CAD files (e.g. DXF, DWG)
- Vision system